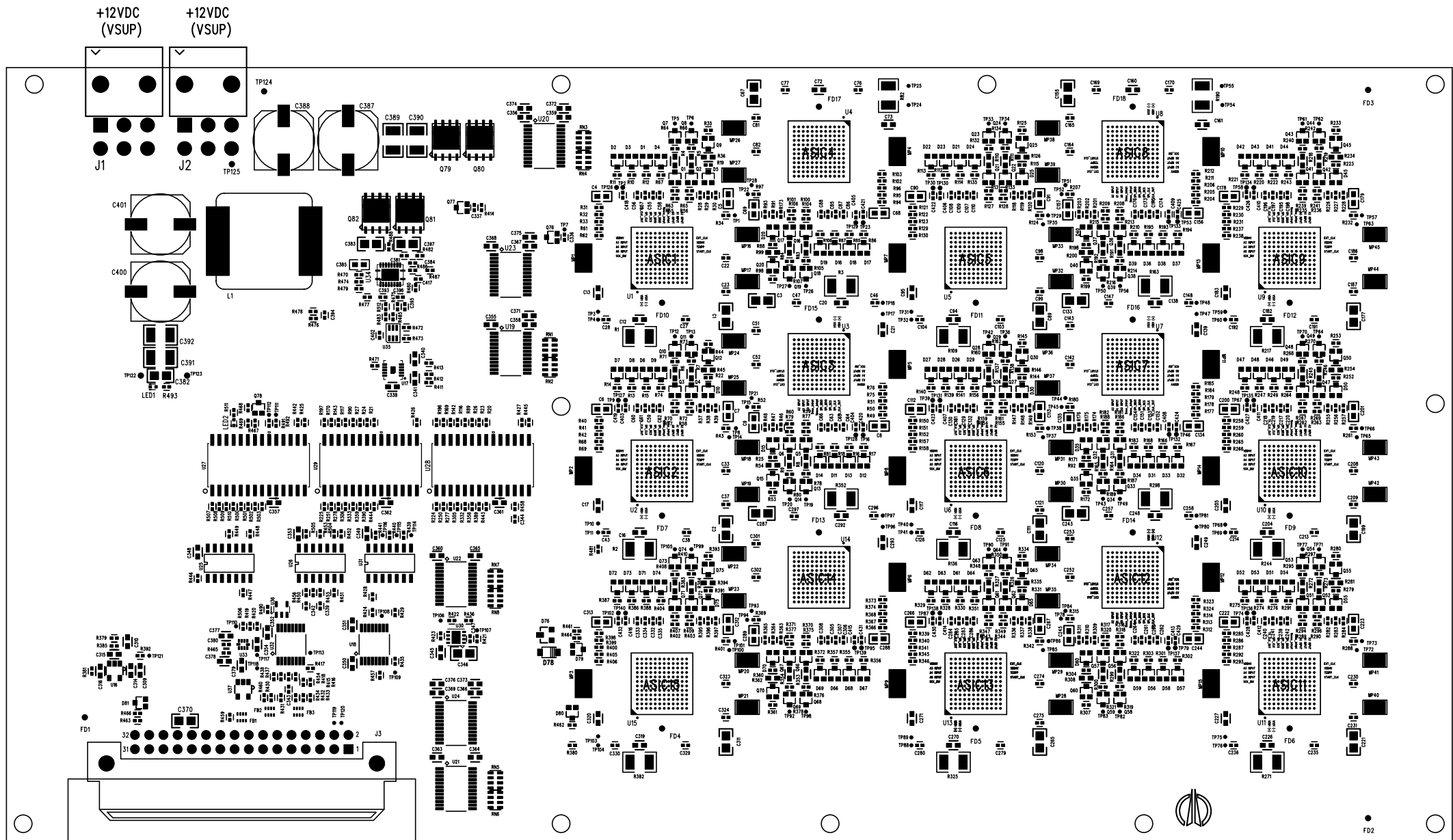


SIA HASHING BOARD 742901R2  
DESIGN INFO 19JUN2018  
TECHEN INC 508-478-0042 tpd  
FABRICATE PER IPC-6012D CLASS II  
MATERIAL PER IPC-4101/126, 8 LAYER, SMOBC (LPI) COLOR RED  
BOARD THICKNESS .062" +/- .007", 1.5 oz. Cu OUTER LAYERS,  
2.0 oz. Cu INNER LAYERS  
DIELECTRIC THICKNESS OUTER CORES = SEE STACKUP DETAIL  
DIELECTRIC THICKNESS CENTER CORE, ADJUST FOR FABRICATION  
TRACE IMPEDANCE- NOT APPLICABLE  
FINISH- IMMERSION GOLD AFTER SOLDERMASK, SILKSCREEN WHITE LPI

BOARD CUTOUTS 11x R1.59mm DRILL CHART UNITS (MILS)				
SIZE	QTY	SYM	PLATED	TOL
12	1160	+	YES	+/- 3.0 MILS
110.24	2	X	NO	+/- 3.0 MILS
16	746	⊠	YES	+/- 3.0 MILS
40	32	◇	YES	+/- 3.0 MILS
8	1941	⊠	YES	+/- 3.0 MILS
14	30	⊠	YES	+/- 3.0 MILS
70	12	+ <sup>A</sup>	YES	+/- 3.0 MILS
118	4	+ <sup>B</sup>	NO	+/- 3.0 MILS

BOARD OVERALL THICKNESS- 0.062" +/- 0.007" [1.575mm +/- 0.118]	
LAYER 1 Cu- 1.5 OZ	DIEL THK - ADJUST FOR MFG
LAYER 2 Cu- 2.0 OZ	DIEL THK ~ 0.005" [0.127mm]
LAYER 3 Cu- 2.0 OZ	DIEL THK ~ 0.005" [0.127mm]
LAYER 4 Cu- 2.0 OZ	DIEL THK ~ 0.005" [0.127mm]
LAYER 5 Cu- 2.0 OZ	DIEL THK - ADJUST FOR MFG
LAYER 6 Cu- 2.0 OZ	DIEL THK ~ 0.005" [0.127mm]
LAYER 7 Cu- 2.0 OZ	DIEL THK ~ 0.005" [0.127mm]
LAYER 8 Cu- 1.5 OZ	DIEL THK ~ 0.005" [0.127mm]



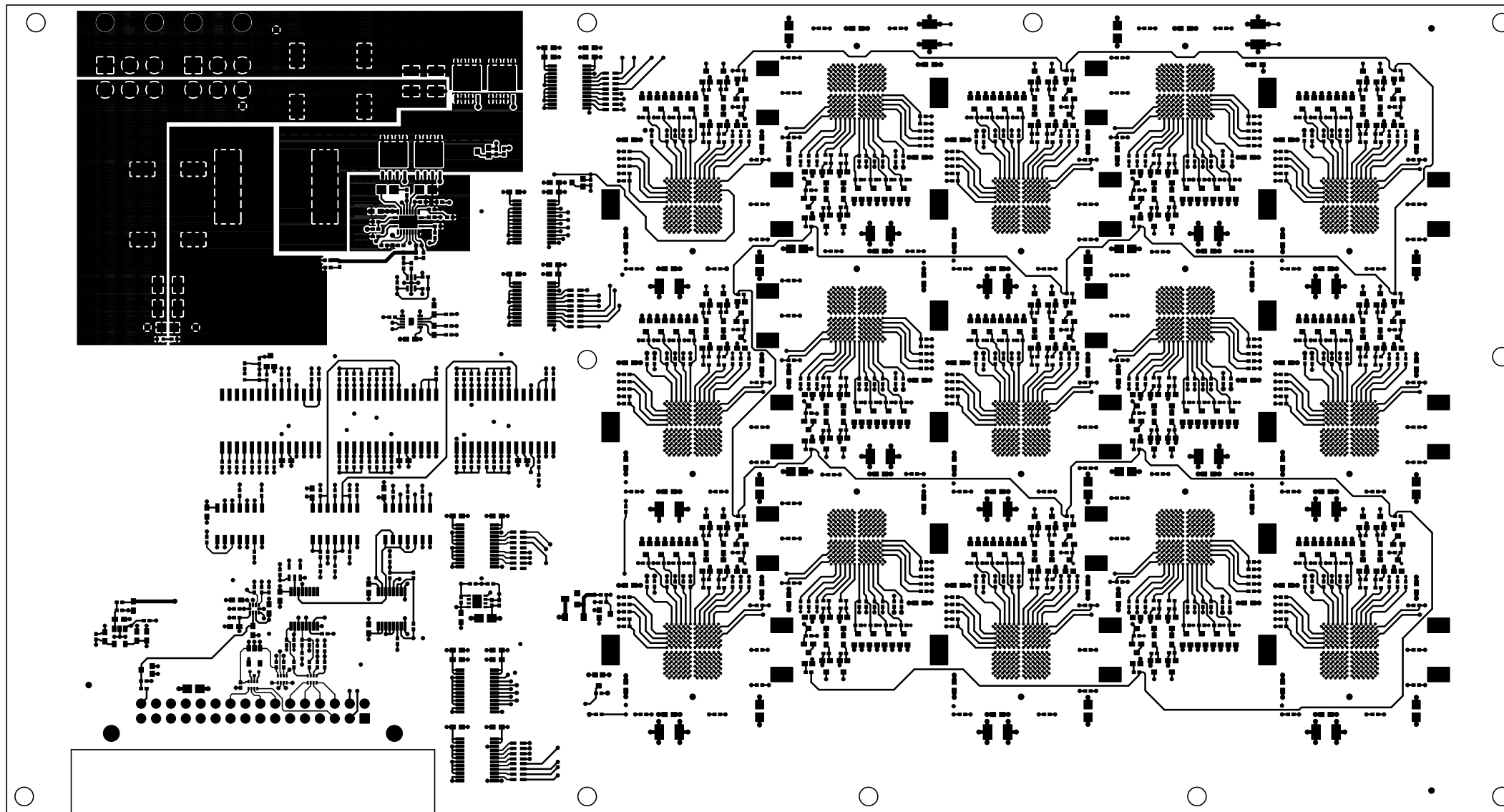
LAYER TOP- PRIMARY COMPONENT ASSY

SIA HASHING BOARD 742901R2  
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TECHEN INC 508-478-0042 tpd  
FABRICATE PER IPC-6012D CLASS II  
MATERIAL PER IPC-4101/126, 8 LAYER, SMOBC (LPI) COLOR RED  
BOARD THICKNESS .062" +/- .007", 1.5 oz. Cu OUTER LAYERS,  
2.0 oz. Cu INNER LAYERS  
DIELECTRIC THICKNESS OUTER CORES = SEE STACKUP DETAIL  
DIELECTRIC THICKNESS CENTER CORE, ADJUST FOR FABRICATION  
TRACE IMPEDANCE- NOT APPLICABLE  
FINISH- IMMERSION GOLD AFTER SOLDERMASK, SILKSCREEN WHITE LPI



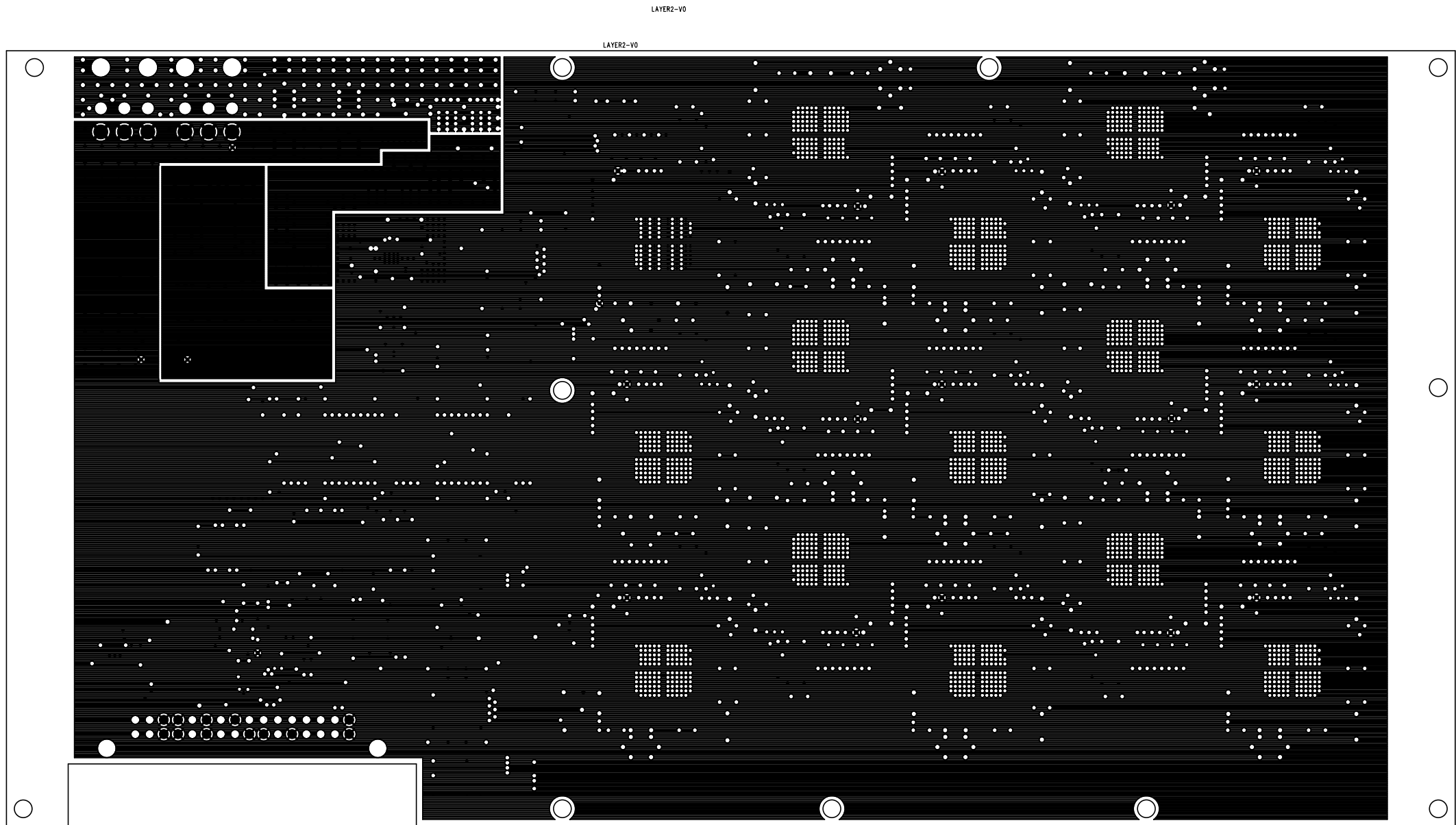
LAYER BOTTOM - SECONDARY COMPONENTS

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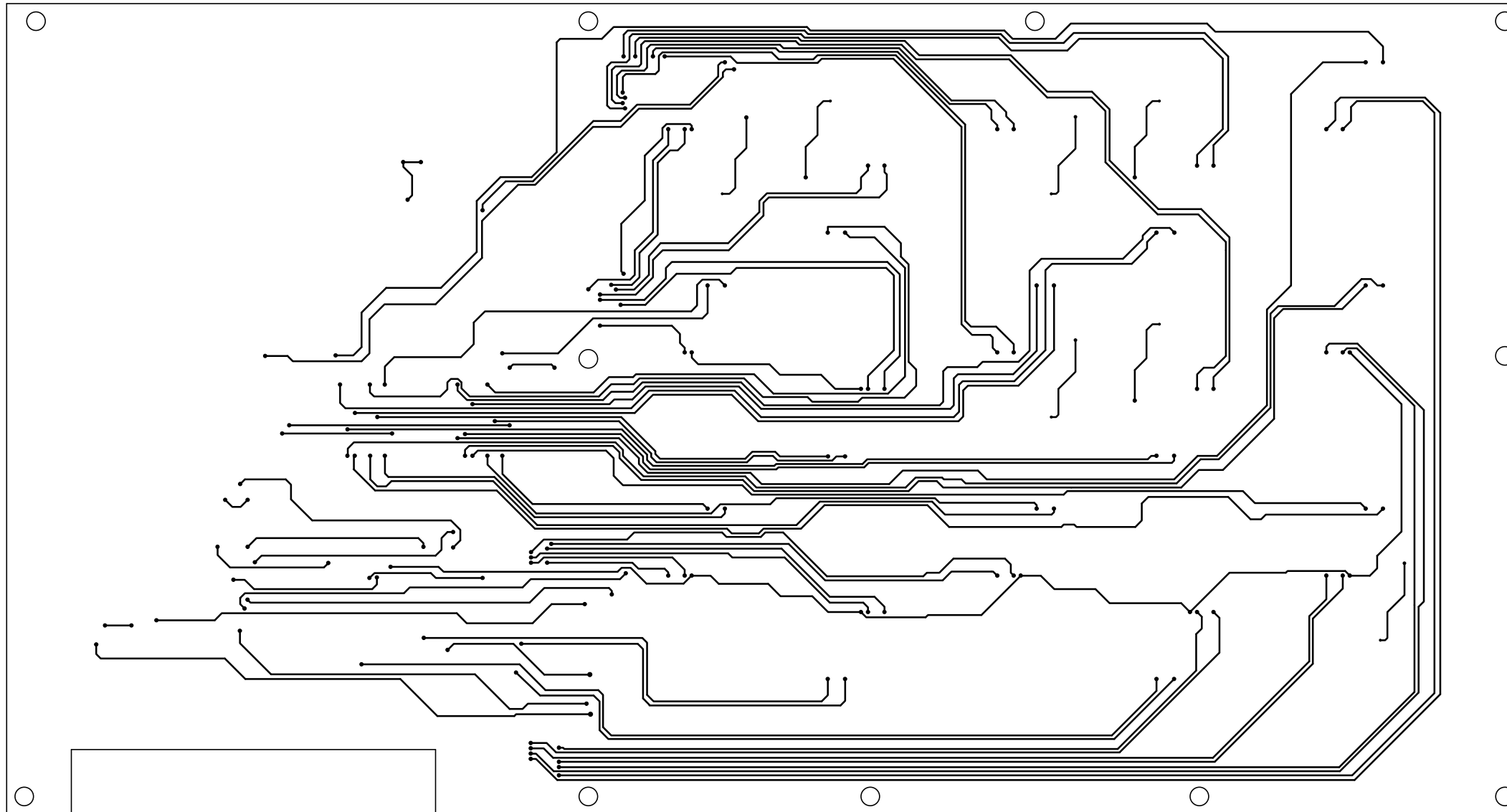
LAYER TOP- PRIMARY COMPONENT

SIA HASHING BOARD 742901R2  
 DESIGN INFO 19JUN2018  
 TECHEN INC 508-478-0042 tpd  
 FABRICATE PER IPC-6012D CLASS II  
 MATERIAL PER IPC-4101/126, 8 LAYER, SMOBC (LPI) COLOR RED  
 BOARD THICKNESS .062" +/- .007", 1.5 oz. Cu OUTER LAYERS,  
 2.0 oz. Cu INNER LAYERS  
 DIELECTRIC THICKNESS OUTER CORES = SEE STACKUP DETAIL  
 DIELECTRIC THICKNESS CENTER CORE, ADJUST FOR FABRICATION  
 TRACE IMPEDANCE- NOT APPLICABLE  
 FINISH- IMMERSION GOLD AFTER SOLDERMASK, SILKSCREEN WHITE LPI



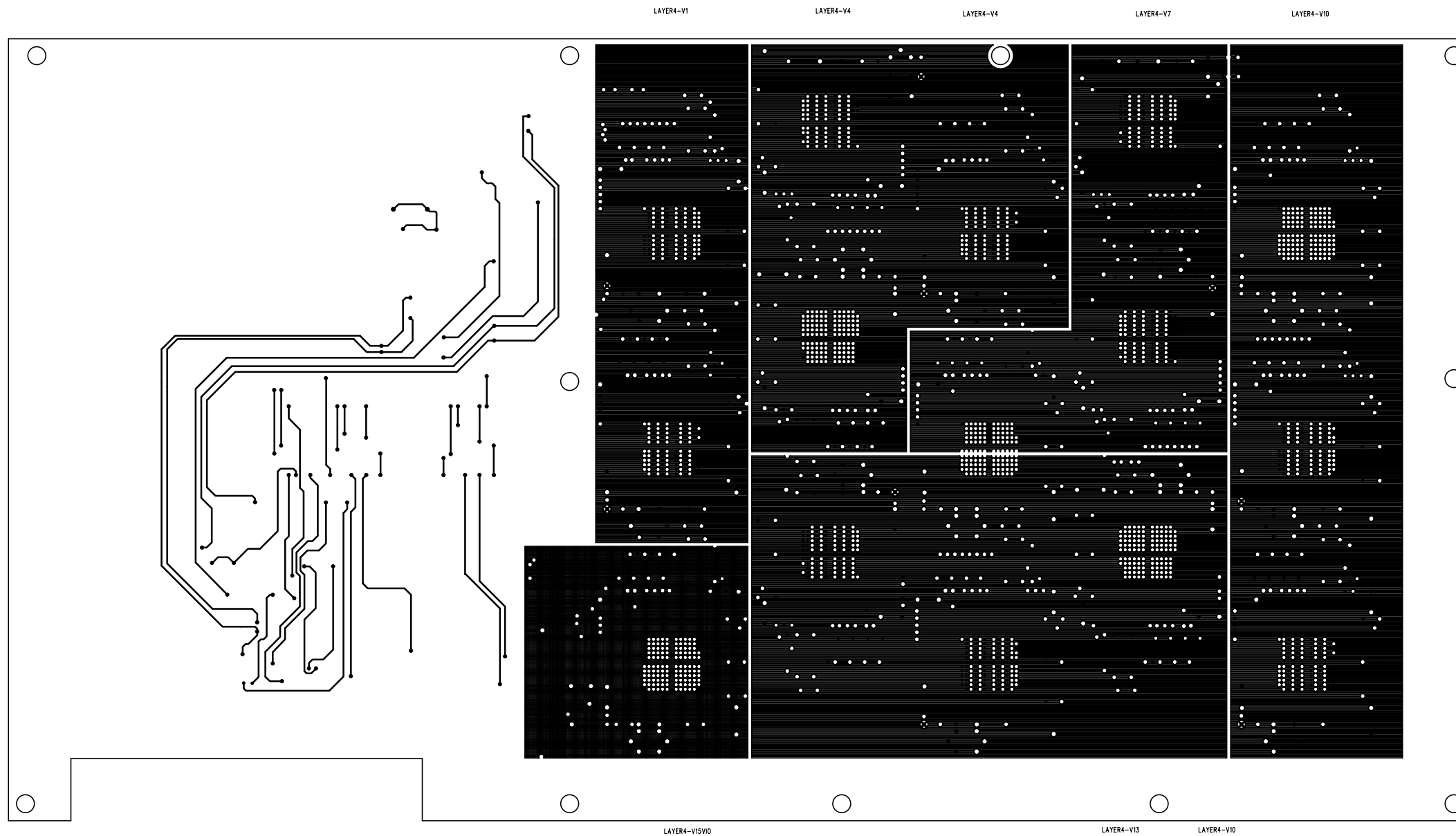
LAYER 2- GND2

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DESIGN INFO 19JUN2018  
TECHEN INC 508-478-0042 tpd  
FABRICATE PER IPC-6012D CLASS II  
MATERIAL PER IPC-4101/126, 8 LAYER, SMOBC (LPI) COLOR RED  
BOARD THICKNESS .062" +/- .007", 1.5 oz. Cu OUTER LAYERS,  
2.0 oz. Cu INNER LAYERS  
DIELECTRIC THICKNESS OUTER CORES = SEE STACKUP DETAIL  
DIELECTRIC THICKNESS CENTER CORE, ADJUST FOR FABRICATION  
TRACE IMPEDANCE- NOT APPLICABLE  
FINISH- IMMERSION GOLD AFTER SOLDERMASK, SILKSCREEN WHITE LPI



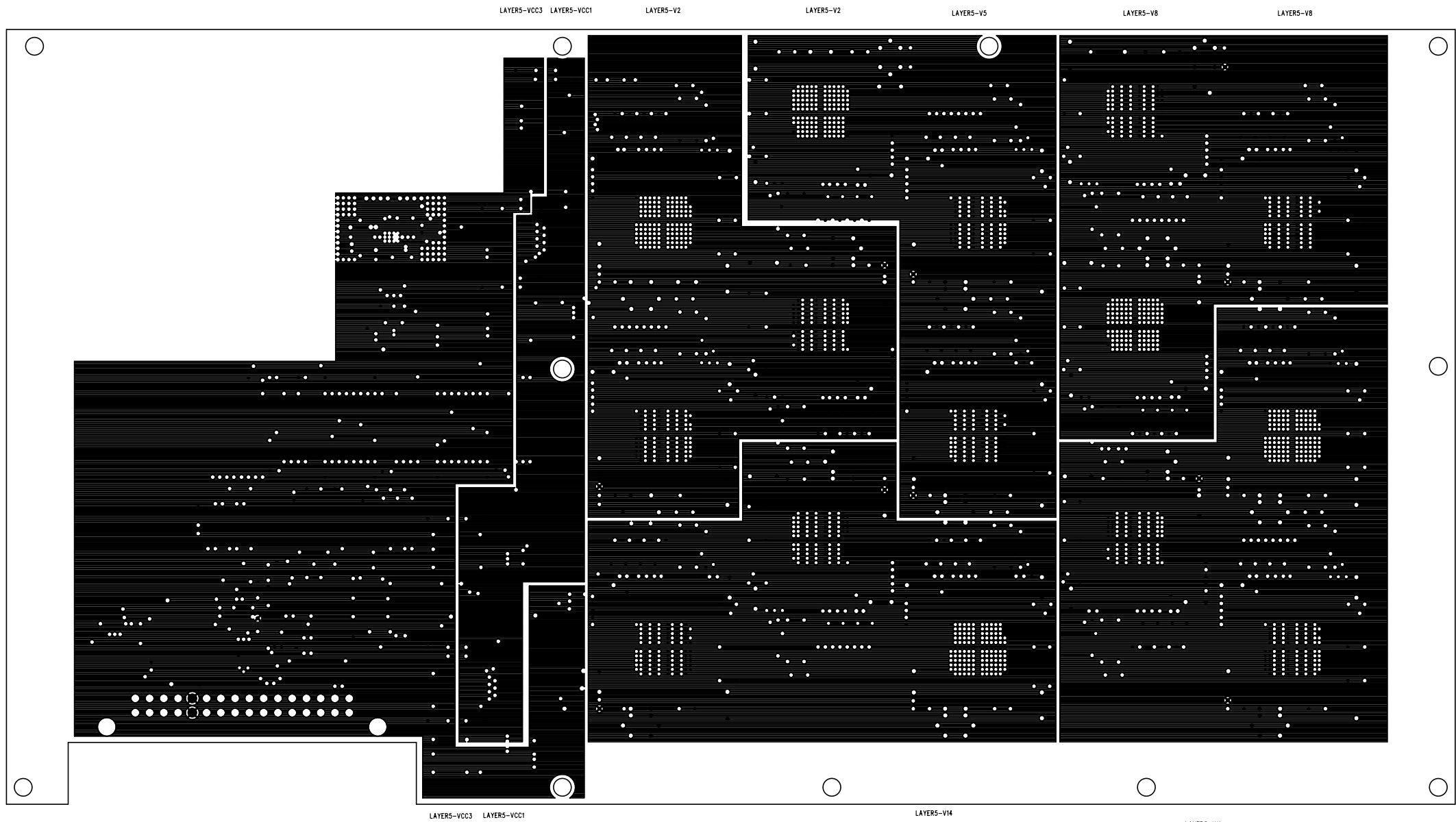
LAYER 3- SIGNAL

SIA HASHING BOARD 742901R2  
 DESIGN INFO 19JUN2018  
 TECHEN INC 508-478-0042 tpd  
 FABRICATE PER IPC-6012D CLASS II  
 MATERIAL PER IPC-4101/126, 8 LAYER, SMOBC (LPI) COLOR RED  
 BOARD THICKNESS .062" +/- .007", 1.5 oz. Cu OUTER LAYERS,  
 2.0 oz. Cu INNER LAYERS  
 DIELECTRIC THICKNESS OUTER CORES = SEE STACKUP DETAIL  
 DIELECTRIC THICKNESS CENTER CORE, ADJUST FOR FABRICATION  
 TRACE IMPEDANCE- NOT APPLICABLE  
 FINISH- IMMERSION GOLD AFTER SOLDERMASK, SILKSCREEN WHITE LPI



LAYER 4 V-A

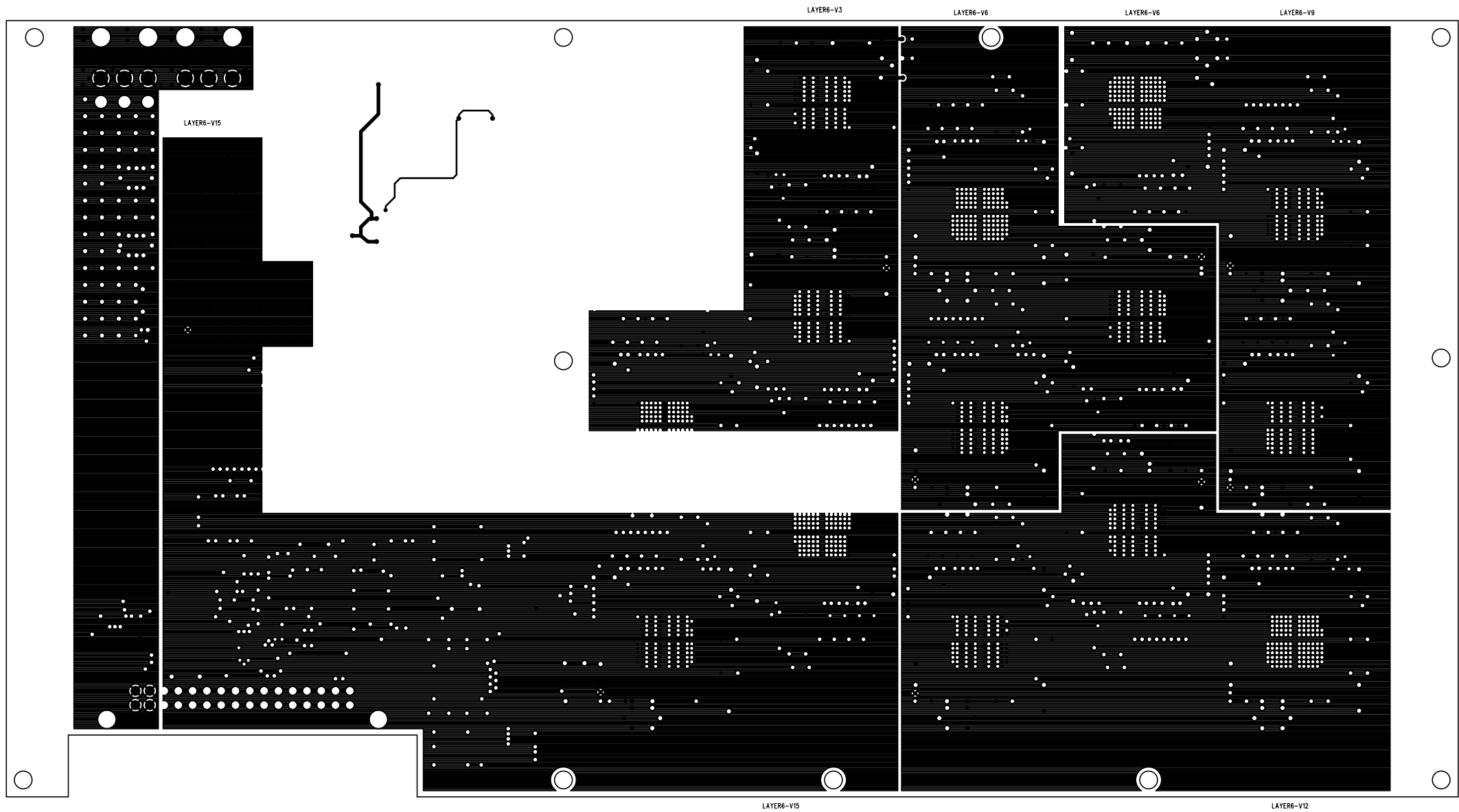
SIA HASHING BOARD 742901R2  
 DESIGN INFO 19JUN2018  
 TECHEN INC 508-478-0042 tpd  
 FABRICATE PER IPC-6012D CLASS II  
 MATERIAL PER IPC-4101/126, 8 LAYER, SMOBC (LPI) COLOR RED  
 BOARD THICKNESS .062" +/- .007", 1.5 oz. Cu OUTER LAYERS,  
 2.0 oz. Cu INNER LAYERS  
 DIELECTRIC THICKNESS OUTER CORES = SEE STACKUP DETAIL  
 DIELECTRIC THICKNESS CENTER CORE, ADJUST FOR FABRICATION  
 TRACE IMPEDANCE- NOT APPLICABLE  
 FINISH- IMMERSION GOLD AFTER SOLDERMASK, SILKSCREEN WHITE LPI



LAYER 5 V-B

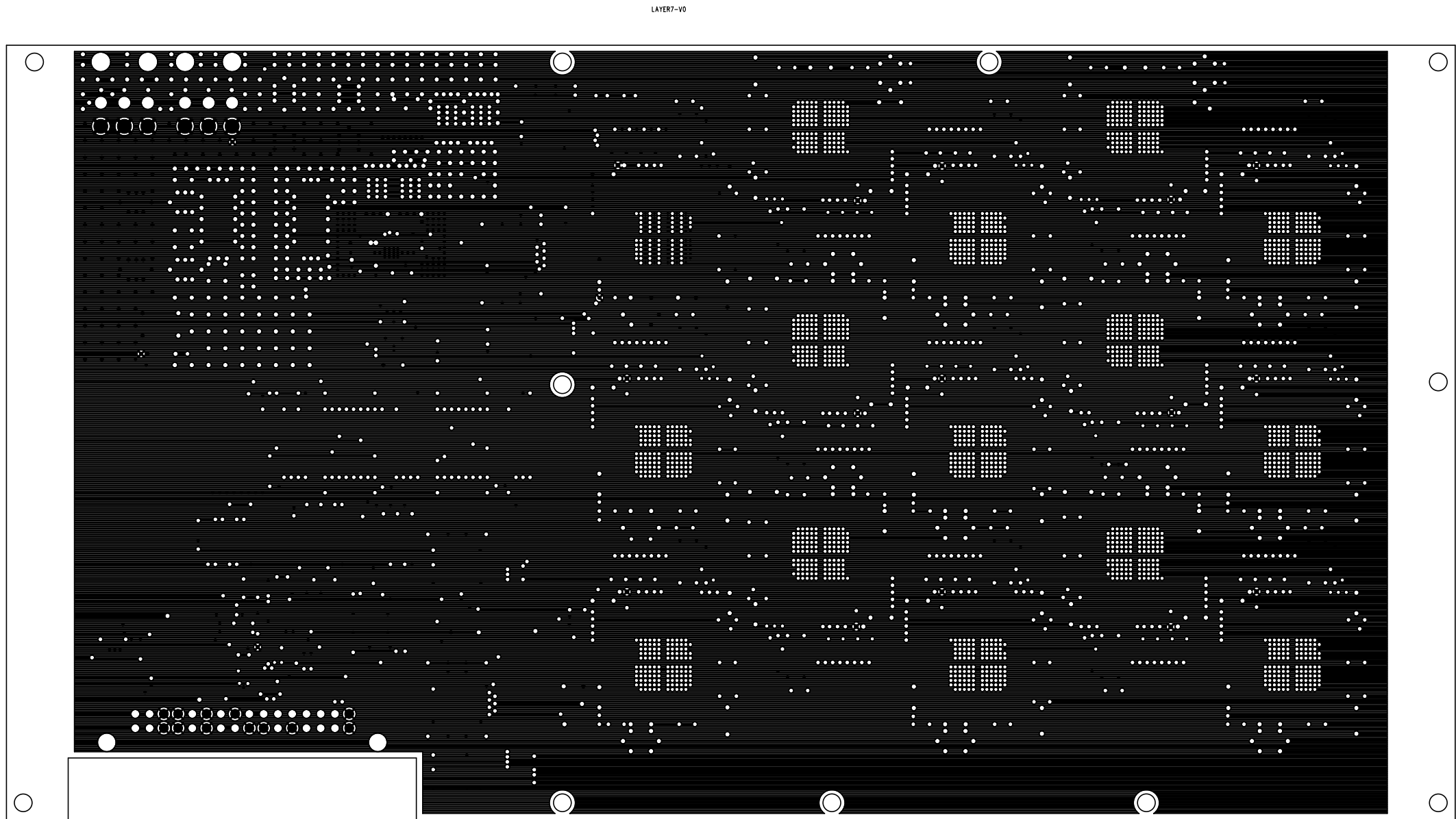
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 DESIGN INFO 19JUN2018  
 TECHEN INC 508-478-0042 tpd  
 FABRICATE PER IPC-6012D CLASS II  
 MATERIAL PER IPC-4101/126, 8 LAYER, SMOBC (LPI) COLOR RED  
 BOARD THICKNESS .062" +/- .007", 1.5 oz. Cu OUTER LAYERS,  
 2.0 oz. Cu INNER LAYERS  
 DIELECTRIC THICKNESS OUTER CORES = SEE STACKUP DETAIL  
 DIELECTRIC THICKNESS CENTER CORE, ADJUST FOR FABRICATION  
 TRACE IMPEDANCE- NOT APPLICABLE  
 FINISH- IMMERSION GOLD AFTER SOLDERMASK, SILKSCREEN WHITE LPI





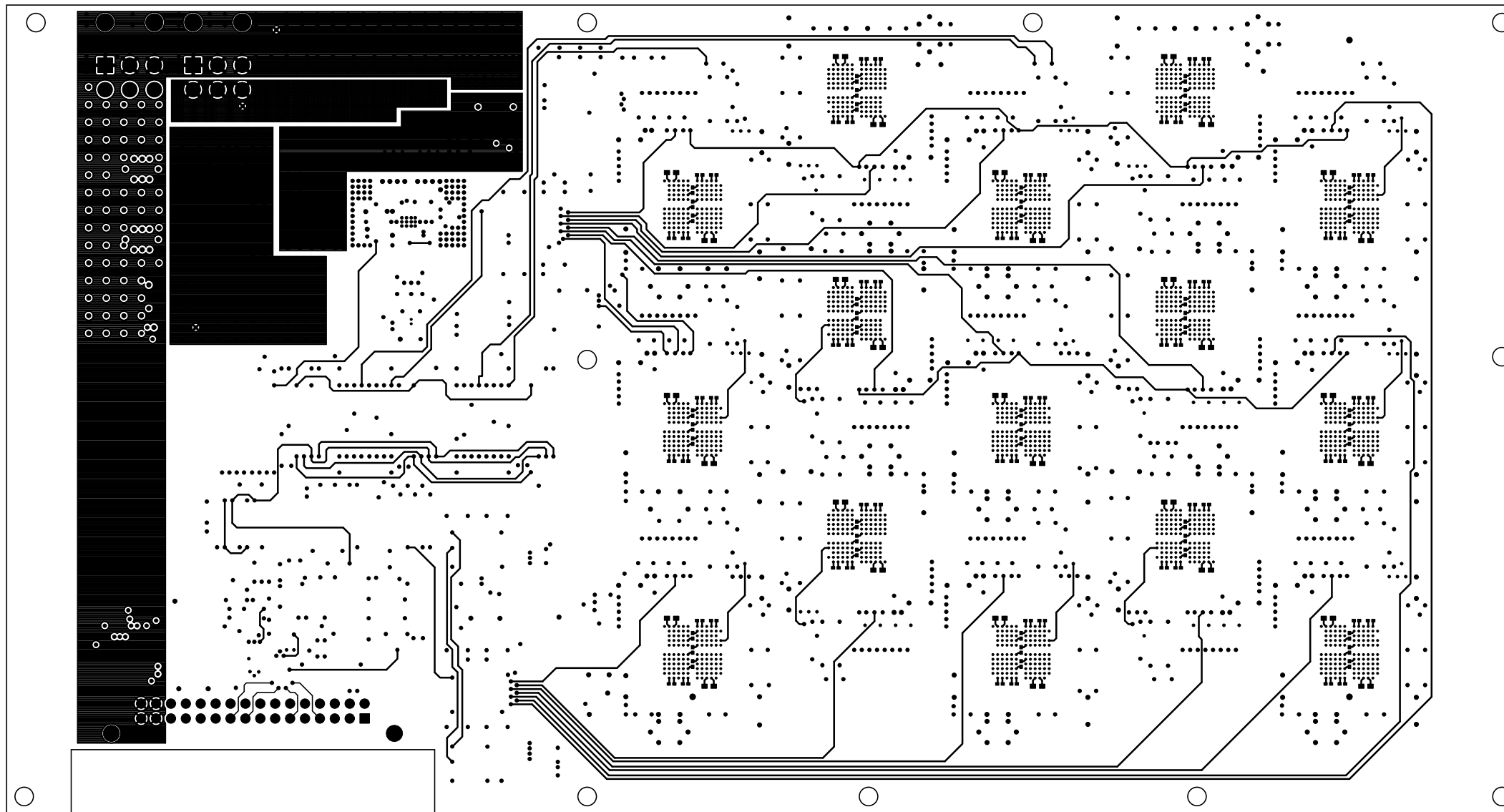
LAYER 6 V-C

SIA HASHING BOARD 742901R2  
DESIGN INFO 19JUN2018  
TECHEN INC 508-478-0042 tpd  
FABRICATE PER IPC-6012D CLASS II  
MATERIAL PER IPC-4101/126, 8 LAYER, SMOBC (LPI) COLOR RED  
BOARD THICKNESS .062" +/- .007", 1.5 oz. Cu OUTER LAYERS,  
2.0 oz. Cu INNER LAYERS  
DIELECTRIC THICKNESS OUTER CORES = SEE STACKUP DETAIL  
DIELECTRIC THICKNESS CENTER CORE, ADJUST FOR FABRICATION  
TRACE IMPEDANCE- NOT APPLICABLE  
FINISH- IMMERSION GOLD AFTER SOLDERMASK, SILKSCREEN WHITE LPI



LAYER 7- GND7

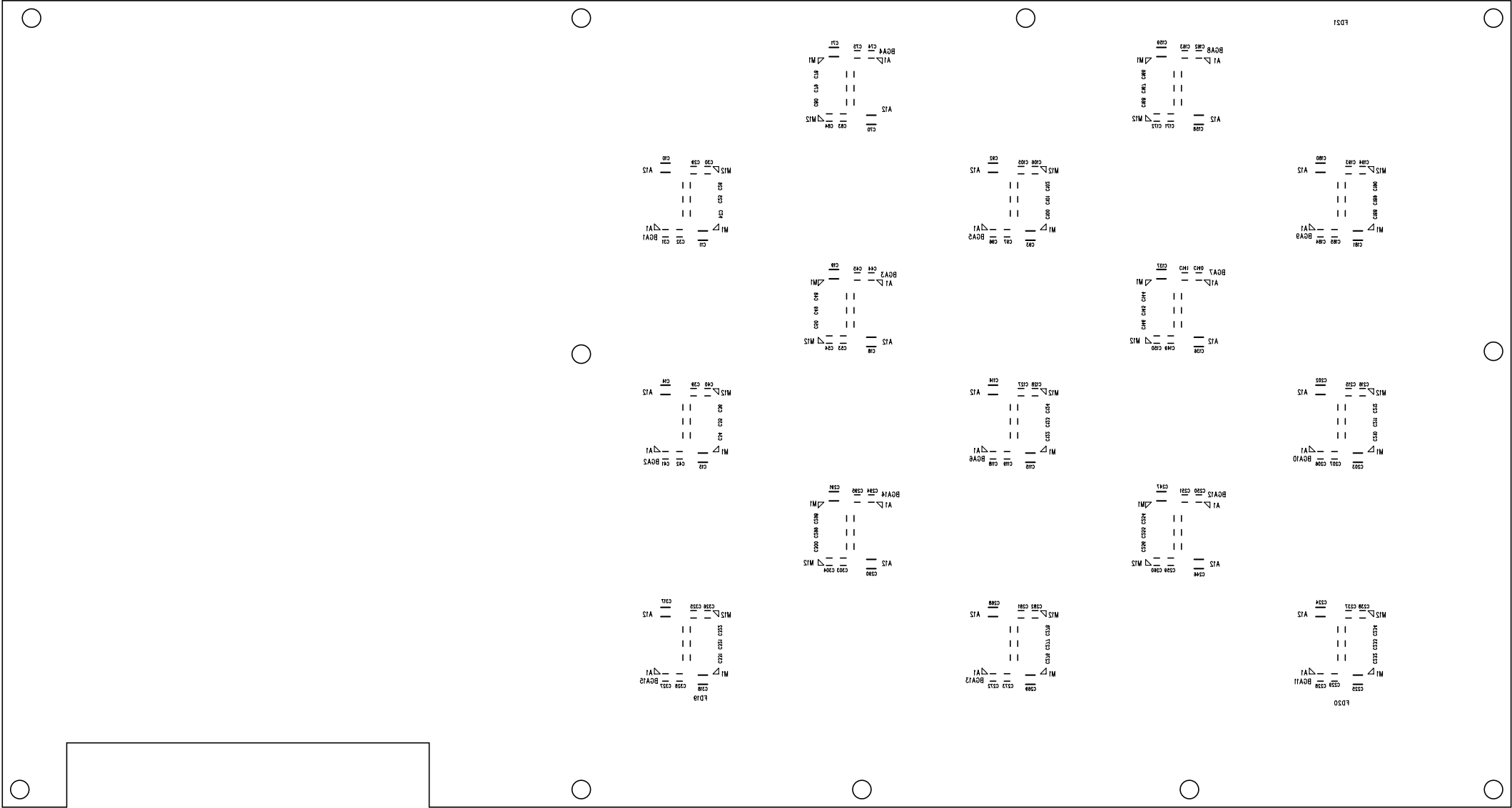
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DESIGN INFO 19JUN2018  
TECHEN INC 508-478-0042 tpd  
FABRICATE PER IPC-6012D CLASS II  
MATERIAL PER IPC-4101/126, 8 LAYER, SMOBC (LPI) COLOR RED  
BOARD THICKNESS .062" +/- .007", 1.5 oz. Cu OUTER LAYERS,  
2.0 oz. Cu INNER LAYERS  
DIELECTRIC THICKNESS OUTER CORES = SEE STACKUP DETAIL  
DIELECTRIC THICKNESS CENTER CORE, ADJUST FOR FABRICATION  
TRACE IMPEDANCE- NOT APPLICABLE  
FINISH- IMMERSION GOLD AFTER SOLDERMASK, SILKSCREEN WHITE LPI



LAYER BOTTOM- SECONDARY COMPONENT

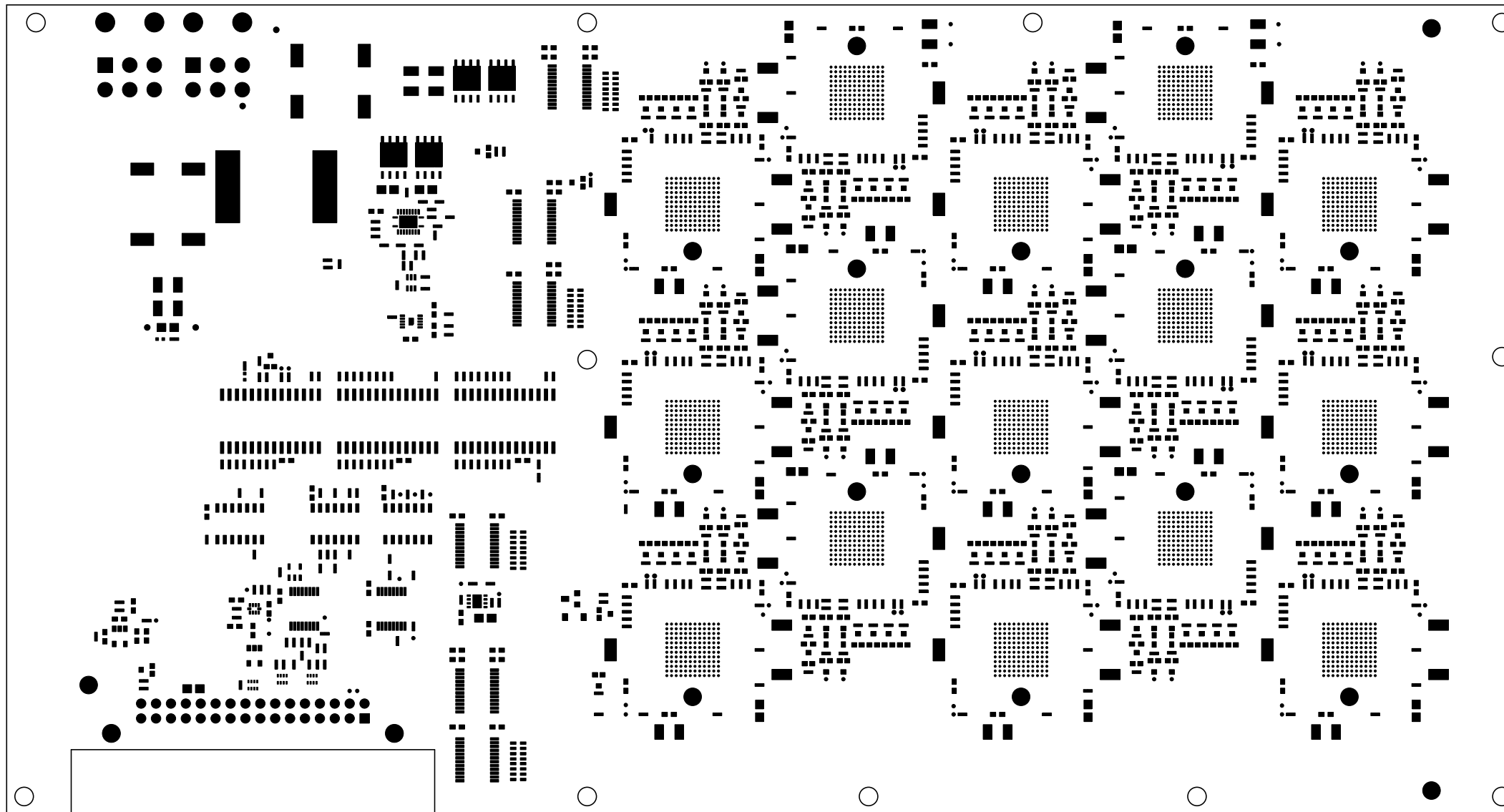
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 DESIGN INFO 19JUN2018  
 TECHEN INC 508-478-0042 tpd  
 FABRICATE PER IPC-6012D CLASS II  
 MATERIAL PER IPC-4101/126, 8 LAYER, SMOBC (LPI) COLOR RED  
 BOARD THICKNESS .062" +/- .007", 1.5 oz. Cu OUTER LAYERS,  
 2.0 oz. Cu INNER LAYERS  
 DIELECTRIC THICKNESS OUTER CORES = SEE STACKUP DETAIL  
 DIELECTRIC THICKNESS CENTER CORE, ADJUST FOR FABRICATION  
 TRACE IMPEDANCE- NOT APPLICABLE  
 FINISH- IMMERSION GOLD AFTER SOLDERMASK, SILKSCREEN WHITE LPI





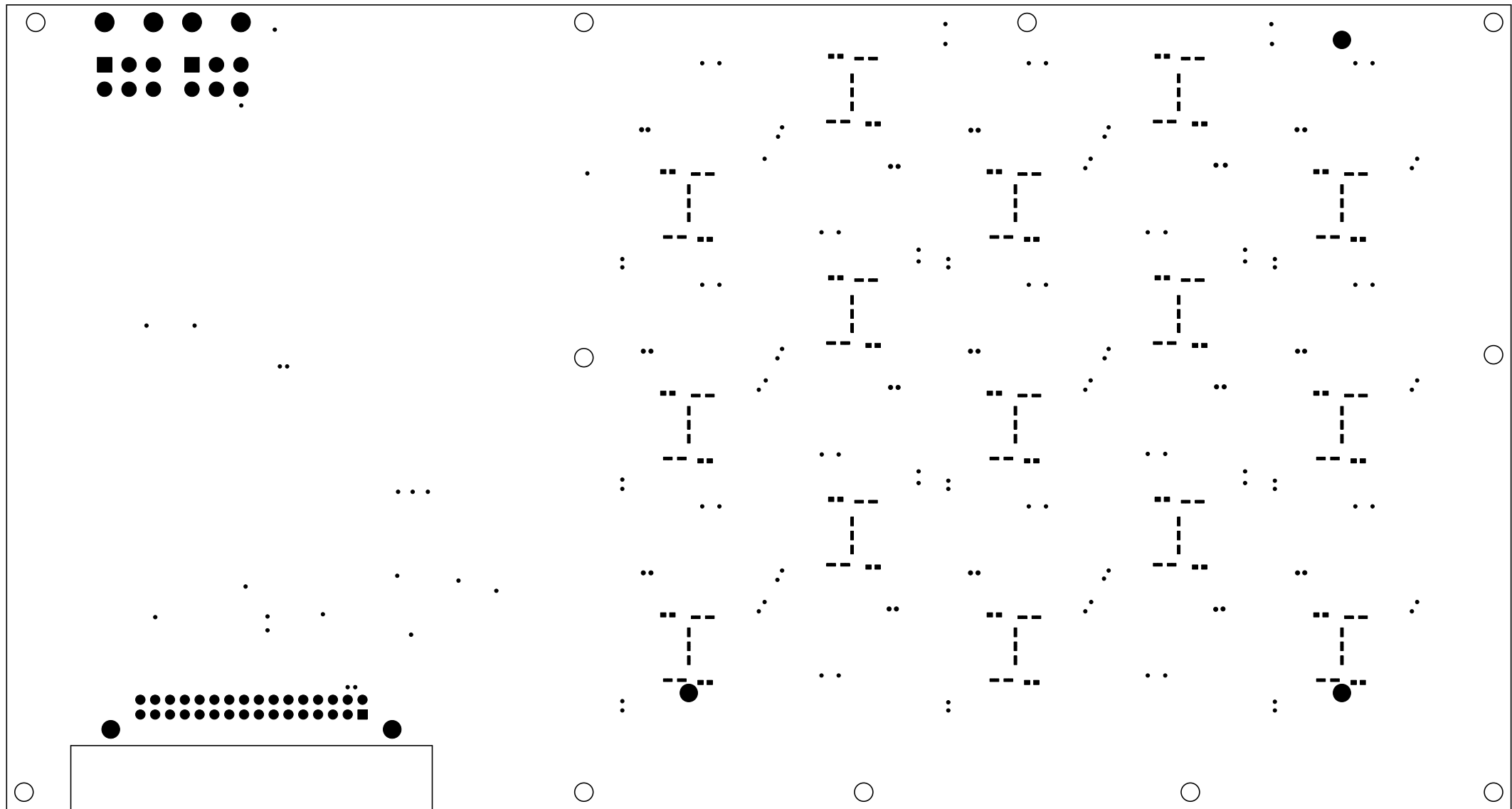
LAYER BOTTOM- SECONDARY COMPONENT  
SILKSCREEN BOTTOM

SIA HASHING BOARD 742901R2  
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FABRICATE PER IPC-6012D CLASS II  
MATERIAL PER IPC-4101/126, 8 LAYER, SMOBC (LPI) COLOR RED  
BOARD THICKNESS .062" +/- .007", 1.5 oz. Cu OUTER LAYERS,  
2.0 oz. Cu INNER LAYERS  
DIELECTRIC THICKNESS OUTER CORES = SEE STACKUP DETAIL  
DIELECTRIC THICKNESS CENTER CORE, ADJUST FOR FABRICATION  
TRACE IMPEDANCE- NOT APPLICABLE  
FINISH- IMMERSION GOLD AFTER SOLDERMASK, SILKSCREEN WHITE LPI



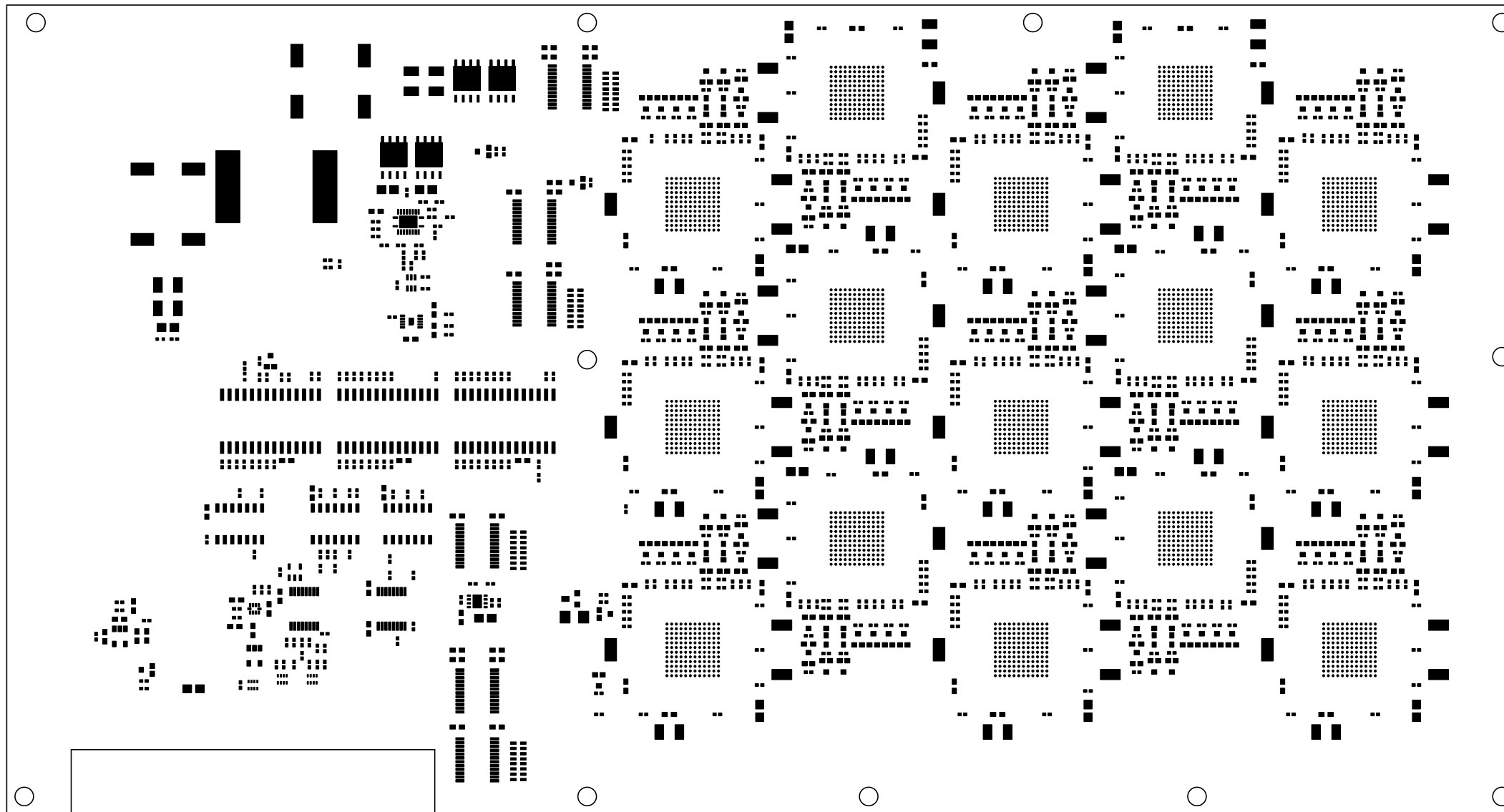
SOLDER MASK TOP

SIA HASHING BOARD 742901R2  
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 FABRICATE PER IPC-6012D CLASS II  
 MATERIAL PER IPC-4101/126, 8 LAYER, SMOBC (LPI) COLOR RED  
 BOARD THICKNESS .062" +/- .007", 1.5 oz. Cu OUTER LAYERS,  
 2.0 oz. Cu INNER LAYERS  
 DIELECTRIC THICKNESS OUTER CORES = SEE STACKUP DETAIL  
 DIELECTRIC THICKNESS CENTER CORE, ADJUST FOR FABRICATION  
 TRACE IMPEDANCE- NOT APPLICABLE  
 FINISH- IMMERSION GOLD AFTER SOLDERMASK, SILKSCREEN WHITE LPI



SOLDER MASK BOTTOM

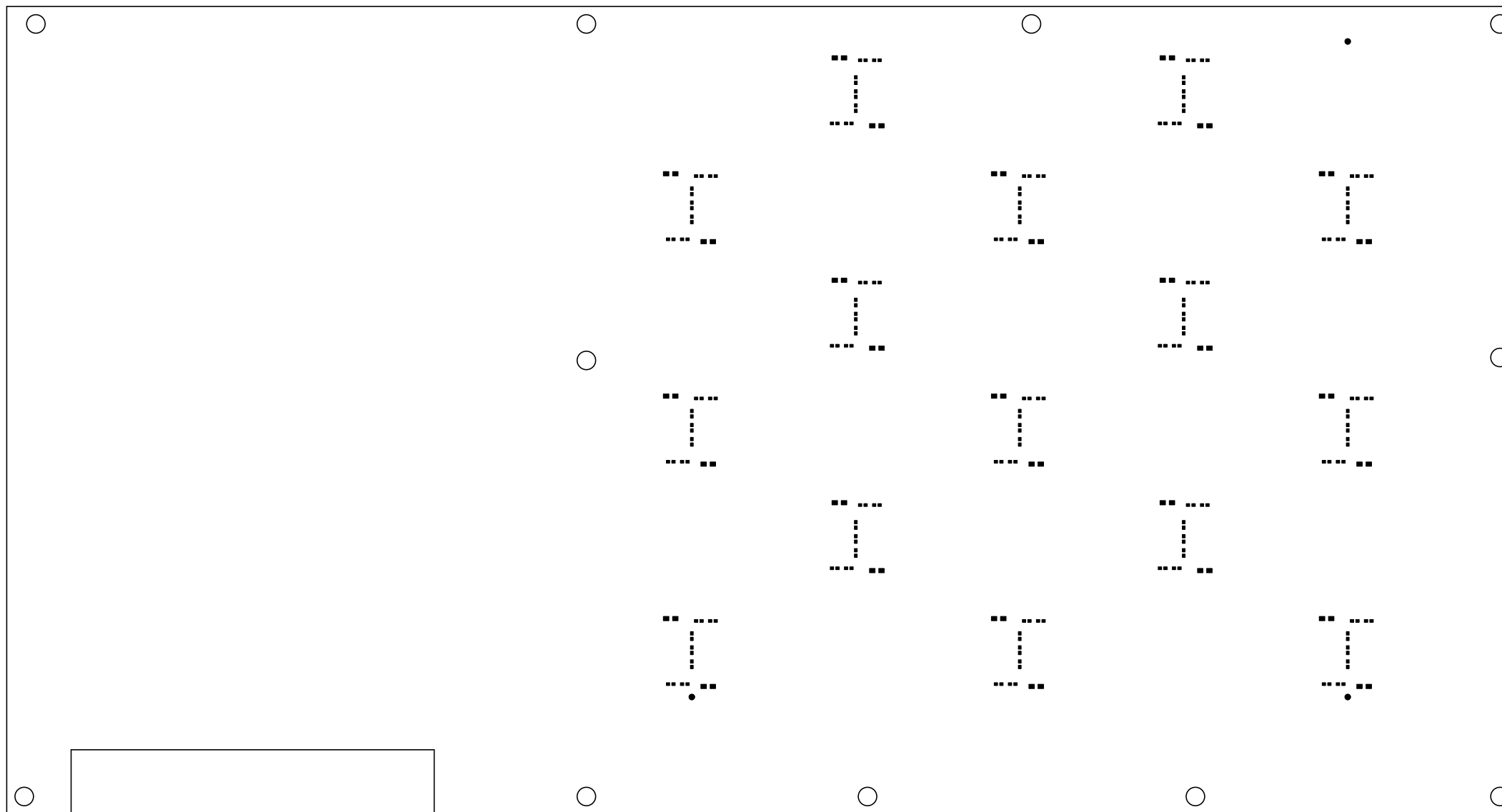
SIA HASHING BOARD 742901R2  
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TECHEN INC 508-478-0042 tpd  
FABRICATE PER IPC-6012D CLASS II  
MATERIAL PER IPC-4101/126, 8 LAYER, SMOBC (LPI) COLOR RED  
BOARD THICKNESS .062" +/- .007", 1.5 oz. Cu OUTER LAYERS,  
2.0 oz. Cu INNER LAYERS  
DIELECTRIC THICKNESS OUTER CORES = SEE STACKUP DETAIL  
DIELECTRIC THICKNESS CENTER CORE, ADJUST FOR FABRICATION  
TRACE IMPEDANCE- NOT APPLICABLE  
FINISH- IMMERSION GOLD AFTER SOLDERMASK, SILKSCREEN WHITE LPI



PASTE MASK TOP

SIA HASHING BOARD 742901R2  
 DESIGN INFO 19JUN2018  
 TECHEN INC 508-478-0042 tpd  
 FABRICATE PER IPC-6012D CLASS II  
 MATERIAL PER IPC-4101/126, 8 LAYER, SMOBC (LPI) COLOR RED  
 BOARD THICKNESS .062" +/- .007", 1.5 oz. Cu OUTER LAYERS,  
 2.0 oz. Cu INNER LAYERS  
 DIELECTRIC THICKNESS OUTER CORES = SEE STACKUP DETAIL  
 DIELECTRIC THICKNESS CENTER CORE, ADJUST FOR FABRICATION  
 TRACE IMPEDANCE- NOT APPLICABLE  
 FINISH- IMMERSION GOLD AFTER SOLDERMASK, SILKSCREEN WHITE LPI





PASTE MASK BOTTOM

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DESIGN INFO 19JUN2018  
TECHEN INC 508-478-0042 tpd  
FABRICATE PER IPC-6012D CLASS II  
MATERIAL PER IPC-4101/126, 8 LAYER, SMOBC (LPI) COLOR RED  
BOARD THICKNESS .062" +/- .007", 1.5 oz. Cu OUTER LAYERS,  
2.0 oz. Cu INNER LAYERS  
DIELECTRIC THICKNESS OUTER CORES = SEE STACKUP DETAIL  
DIELECTRIC THICKNESS CENTER CORE, ADJUST FOR FABRICATION  
TRACE IMPEDANCE- NOT APPLICABLE  
FINISH- IMMERSION GOLD AFTER SOLDERMASK, SILKSCREEN WHITE LPI

